

This document is the property of Amphenol Corporation and is delivered on the express condition that it not be disclosed, reproduced or used, in whole or in part, for manufacture or sale by anyone other than Amphenol Corporation without its prior consent, and that no right is granted to disclose or to use any information in this document.

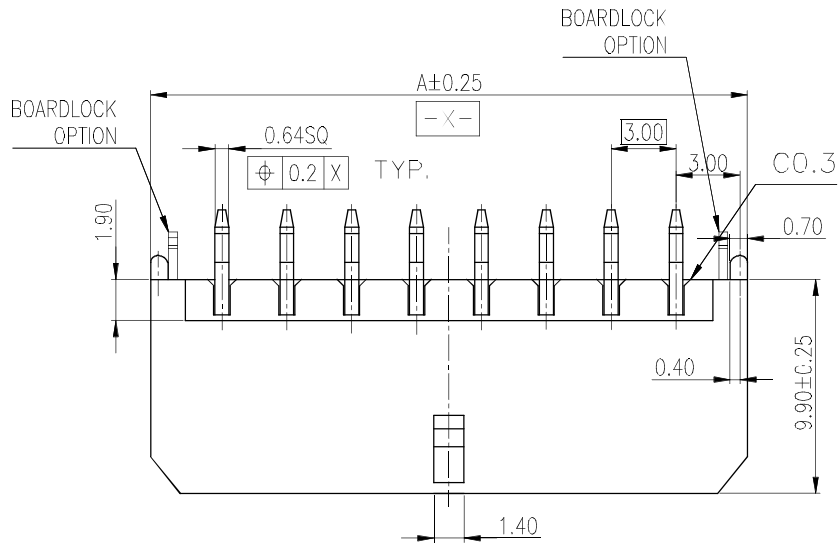
The marking on this product doesn't contain environmental hazardous materials per Material Specification SS-00259 for Sony GP compliant or per directive 2011/65/EC for RoHS compliant.



ORIGINAL



REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A		RELEASE FOR RoHS	07/04/2006	Armstrong Kod
B	NE-06295	MODIFIED DRAWING	09/06/2006	Edward Wu
C	NE-09209	MODIFIED DRAWING	12/30/2009	Arron Lin
D	NE-10003	MODIFIED DRAWING	01/07/2010	Arron Lin
E	NE-10028	ADD LOCK KEY DIMENSION	03/04/2010	Roger Tsai
F	NE-11043	MODIFIED DRAWING	03/28/2010	Arron Lin
A1	NE-11069	ADD PLATING OPTIONS AND POS P/N INTO DRAWING	06/07/2011	Arron Lin
B1	NE-11120	MODIFY THE DESCRIPTION	09/02/2011	Arron Lin
C1	NE-12012	ADDED POST DIM. 0.95	01/31/2012	Arron Lin
D1	NE-12023	DIMENSION 1.98 CHANGED TO 2.05mm	02/21/2012	Arron Lin
E1	NE-12113	REMOVE 2 POS OPTIONS AND UPDATE PACKING QUANTITY.	07/04/2012	Arron Lin
F1	NE-13034	MODIFY PLATING TO OVERALL	03/13/2013	Arron Lin
A2	NE-13197	ADDED DIM & UPDATE FINISH NOTE	12/06/2013	Arron Lin
B2	NE-15054	ADD 2PIN AND UPDATE PACKING	04/29/2015	Roger Tsai
C2	NE-15114	ADD BOARDLOCK OPTION	09/15/2015	Roger Tsai



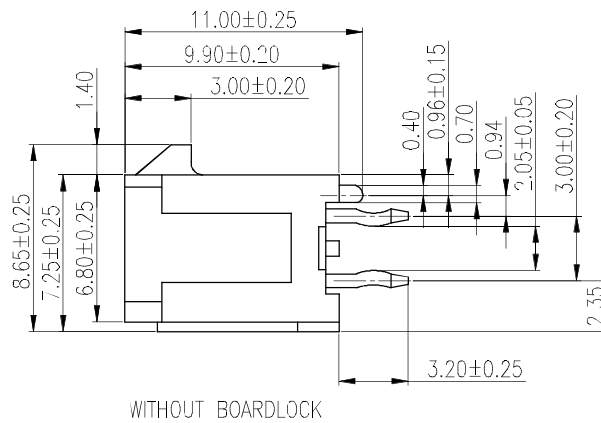
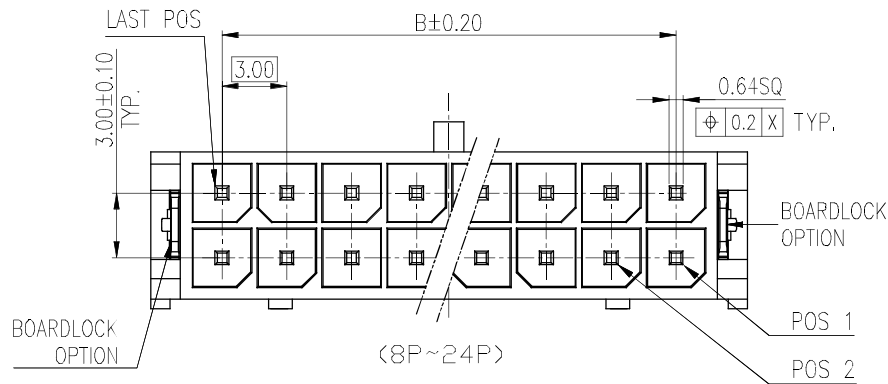
PART NO. G881AX11XXTEU

No. OF CIRCUIT — BOARDLOCK
 1: W/BOARDLOCK
 2: W/O BOARDLOCK

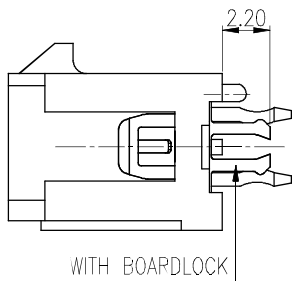
CONTACT FINISH
 0: Tin (OVERALL)
 1: FLASH GOLD (OVERALL)
 2: 15 μ" GOLD
 3: 30 μ" GOLD

NOTE:

- INSULATOR: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0, COLOR: BLACK.
- CONTACT MATERIAL: COPPER ALLOY;
- FINISH:
 CONTACT: SELECTIVE PLATING. ;
 SOLDERING AREA: MATTE TIN 100μ" MIN. OR GOLD PLATING;
 UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
- THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EC FOR RoHS.
- PACKING MUST BE PER AMPHENOL PACKING SPECIFICATION



24	39.60	33.00	39.00	37.3
22	36.60	30.00	36.00	34.3
20	33.60	27.00	33.00	31.3
18	30.60	24.00	30.00	28.3
16	27.60	21.00	27.00	25.3
14	24.60	18.00	24.00	22.3
12	21.60	15.00	21.00	19.3
10	18.60	12.00	18.00	16.3
08	15.60	9.00	15.00	13.3
06	12.60	6.00	12.00	10.3
04	9.60	3.00	9.00	7.3
02	6.60		6.00	4.3
NO. OF CIRCUIT	A	B	C	D



TOLERANCE	APPROVALS	DATE	TITLE		PART No.			
X. X.X ±0.30 X.XX ±0.20 X.XXX ±0.10	DRAWN Aqua Chou	09/15/2015	G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT PCB MOUNT		G881AXX1XXTEU			
ANGULAR ±1°	CHECKED Roger Tsai	09/15/2015	APPROVED Roger Tsai		UNIT mm	SIZE A3	PART No. G881AXX1XXTEU	
UNLESS OTHERWISE SPECIFIED	DWG TYPE CUST DWG	PROJECT CODE PHD	SCALE NA		SHEET 1 OF 3	DWG No. G881AXX1XXTEU		REV. C2

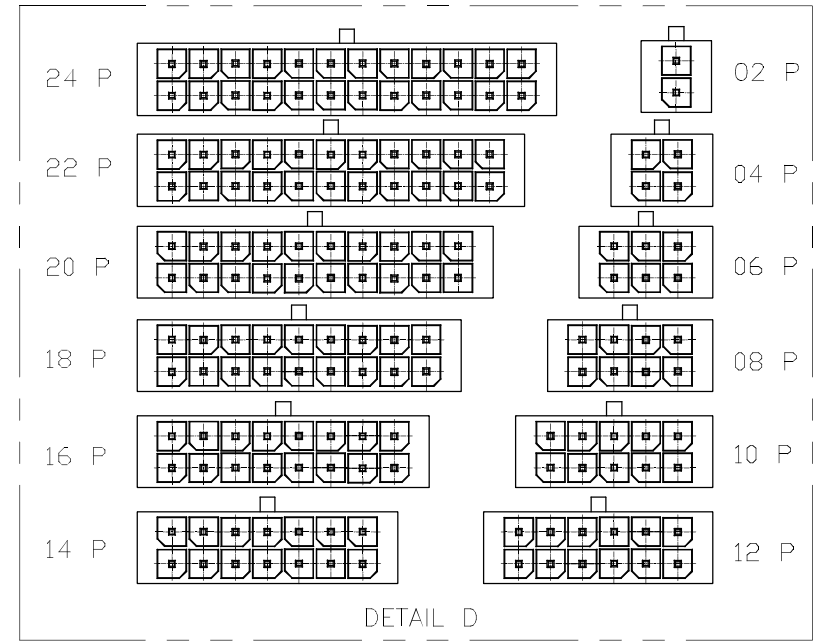
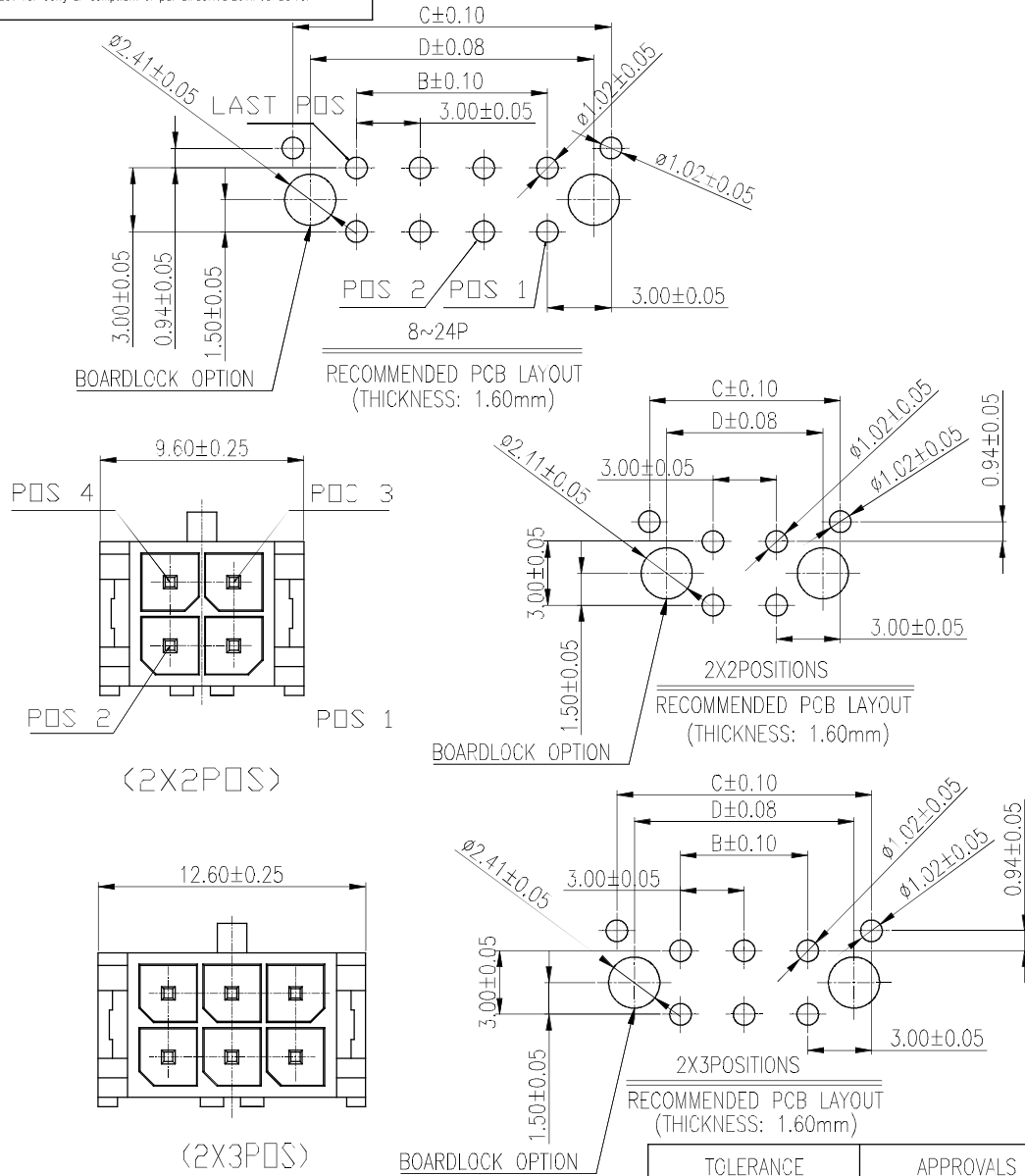
This document is the property of Amphenol Corporation and is delivered on the express condition that it not be disclosed, reproduced or used, in whole or in part, for manufacture or sale by anyone other than Amphenol Corporation without its prior consent, and that no right is granted to disclose or to use any information in this document.

The marking on this product doesn't contain environmental hazardous materials per Material Specification SS-00259 for Sony GP compliant or per directive 2011/65/EC for RoHS compliant.

ORIGINAL



REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A		RELEASE FOR RoHS	07/04/2006	Armstrong Kod
B	NE-06295	MODIFIED DRAWING	09/06/2006	Edward Wu
C	NE-09209	MODIFIED DRAWING	12/30/2009	Arron Lin
D	NE-10003	MODIFIED DRAWING	01/07/2010	Arron Lin
E	NE-10028	ADD LOCK KEY DIMENSION	03/04/2010	Roger Tsai
F	NE-11043	MODIFIED DRAWING	03/28/2010	Arron Lin
A1	NE-11069	ADD PLATING OPTIONS AND POS P/N INTO DRAWING	06/07/2011	Arron Lin
B1	NE-11120	MODIFY THE DESCRIPTION	09/02/2011	Arron Lin
C1	NE-12012	ADDED POST DIM. 0.95	01/31/2012	Arron Lin
D1	NE-12023	DIMENSION 1.98 CHANGED TO 2.05mm	02/21/2012	Arron Lin
E1	NE-12113	REMOVE 2 POS OPTIONS AND UPDATE PACKING QUANTITY.	07/04/2012	Arron Lin
F1	NE-13034	MODIFY PLATING TO OVERALL	03/13/2013	Arron Lin
A2	NE-13197	ADDED DIM & UPDATE FINISH NOTE	12/06/2013	Arron Lin
B2	NE-15054	ADD 2PIN AND UPDATE PACKING	04/29/2015	Roger Tsai
C2	NE-15114	ADD BOARDLOCK OPTION	09/15/2015	Roger Tsai



TOLERANCE	APPROVALS	DATE	TITLE		PART No.			
X. ±0.30	DRAWN Aqua Chou	09/15/2015	G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT PCB MOUNT		Amphenol® Amphenol Corporation Amphenol Taiwan Corporation			
X.X ±0.20	CHECKED Roger Tsai	09/15/2015						
X.XX ±0.10	APPROVED Roger Tsai	09/15/2015						
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD	UNIT mm	SIZE A3	PART No. G881AXX1XXTEU			
UNLESS OTHERWISE SPECIFIED			SCALE NA	SHEET 2 OF 3	DWG No. G881AXX1XXTEU REV. C2			

This document is the property of Amphenol Corporation and is delivered on the express condition that it not be disclosed, reproduced or used, in whole or in part, for manufacture or sale by anyone other than Amphenol Corporation without its prior consent, and that no right is granted to disclose or to use any information in this document.

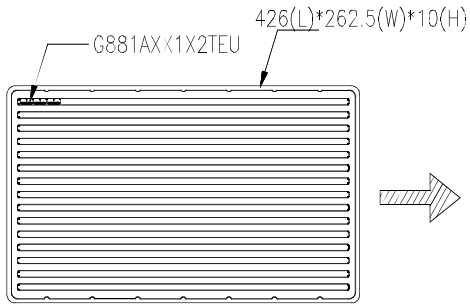
The marking on this product doesn't contain environmental hazardous materials per Material Specification SS-00259 for Sony GP compliant or per directive 2011/65/EC for RoHS compliant.



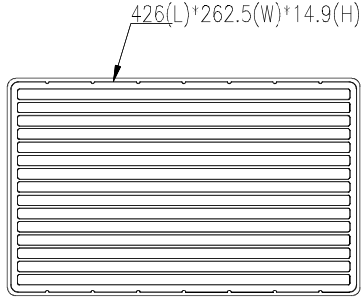
ORIGINAL



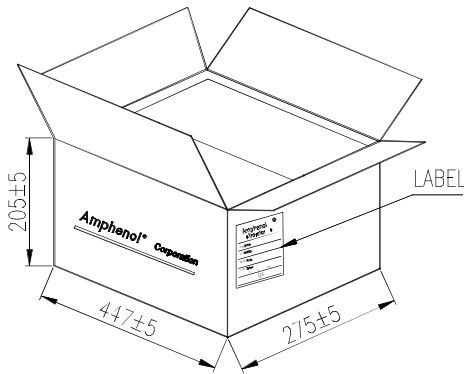
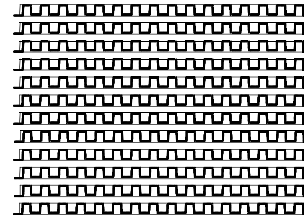
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A		RELEASE FOR RoHS	07/04/2006	Armstrong Koo
B	NE-06295	MODIFIED DRAWING	09/06/2006	Edward Wu
C	NE-09209	MODIFIED DRAWING	12/30/2009	Arron Lin
D	NE-10003	MODIFIED DRAWING	01/07/2010	Arron Lin
E	NE-10028	ADD LOCK KEY DIMENSION	03/04/2010	Roger Tsai
F	NE-11043	MODIFIED DRAWING	03/28/2010	Arron Lin
A1	NE-11069	ADD PLATING OPTIONS AND POS P/N INTO DRAWING	06/07/2011	Arron Lin
B1	NE-11120	MODIFY THE DESCRIPTION	09/02/2011	Arron Lin
C1	NE-12012	ADDED POST DIM. 0.95	01/31/2012	Arron Lin
D1	NE-12023	DIMENSION 1.98 CHANGED TO 2.05mm	02/21/2012	Arron Lin
E1	NE-12113	REMOVE 2 POS OPTIONS AND UPDATE PACKING QUANTITY.	07/04/2012	Arron Lin
F1	NE-13034	MODIFY PLATING TO OVERALL	03/13/2013	Arron Lin
A2	NE-13197	ADDED DIM & UPDATE FINISH NOTE	12/06/2013	Arron Lin
B2	NE-15054	ADD 2PIN AND UPDATE PACKING	04/29/2015	Roger Tsai
C2	NE-15114	ADD BOARDLOCK OPTION	09/15/2015	Roger Tsai



TRAY BOTTOM COVER



TRAY TOP COVER



(12 INSIDE CARTON)

POS	PCS/TRAY	PCS/CARTON
02	900	10800
04	615	7380
06	465	5580
08	375	4500
10	315	3780
12	270	3240
14	240	2880
16	210	2520
18	180	2160
20	165	1980
22	150	1800
24	150	1800

- NOTE:
- MATERIAL : TRANSPARENT CONDUCTIVE POLYSTYRENE ALLOY
 - ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
 - THICKNESS : 0.80±0.05mm.

TOLERANCE	APPROVALS	DATE	TITLE		Amphenol [®]	
X. ±0.30	DRAWN Aqua Chou	09/15/2015	G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT PCB MOUNT		Amphenol Corporation Amphenol Taiwan Corporation	
X.X ±0.20	CHECKED Roger Tsai	09/15/2015				
X.XX ±0.10	APPROVED Roger Tsai	09/15/2015				
ANGULAR ±1°	DWG TYPE CUST DWG	PROJECT CODE PHD	UNIT mm	SIZE A3	PART No. G881AXX1XXTEU	
UNLESS OTHERWISE SPECIFIED			SCALE NA	SHEET 3 OF 3	DWG No. G881AXX1XXTEU	REV. C2